

Title (en)

POLISHING PAD WITH FLOATING ELEMENTS AND METHOD OF MAKING AND USING THE SAME

Title (de)

POLIERKISSEN MIT SCHWIMMENDEN ELEMENTEN UND HERSTELLUNGS- UND VERWENDUNGSVERFAHREN DAFÜR

Title (fr)

TAMPON DE POLISSAGE AVEC ELEMENTS FLOTTANTS, ET PROCEDE DE FABRICATION ET D'UTILISATION DE CEUX-CI

Publication

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Application

**EP 09790596 A 20090717**

Priority

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Abstract (en)

[origin: WO2010009420A1] The disclosure is directed to polishing pads with floating polishing elements bonded to a support layer, for example by thermal bonding, and to methods of making and using such pads in a polishing process. In one exemplary embodiment, the polishing pad includes a multiplicity of polishing elements, at least some of which may be porous, each polishing element affixed to a major surface of a support layer so as to restrict lateral movement of the polishing elements with respect to one or more of the other polishing elements, but remaining moveable in an axis substantially normal to the support layer. In certain embodiments, the polishing pad may additionally include a compliant layer affixed to the support layer opposite the polishing elements, and optionally, a polishing composition distribution layer. In some embodiments using porous polishing elements, the pores are distributed substantially at a polishing surface of the polishing elements.

IPC 8 full level

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